

## D I D Y O U K N O W

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*Did you know that in some parts of the world, it is illegal to collect water falling from the sky? It hasn't even touched the ground yet.*

*Did you know that a farmer can grow corn from seed, watch it grow in their own field under their own sun, and owe a licensing fee to a corporation for what grew — because a patent was filed on the genetic sequence inside the seed? The earth became a license violation.*

*Did you know that nations are currently acquiring territory — not for its land, not for its people — but for the minerals under it? Silicon. Gallium. Germanium. The raw material of chips. The ground itself is being enclosed before what's in it has even been named.*

**Now you know.**

*What follows is offered in response.*

## OPEN HARDWARE PUBLICATION

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# MODULAR THERMAL FLYWHEEL STACK AND GRADIENT GOVERNANCE SYSTEM

*Material-Agnostic Thermal Management Architecture | Micro, Meso, and Macro Scale*

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**Origin:** 39 North LLC | Interpretive Architecture

**Published:** March 2026

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*“The design is the gift. The material is whoever’s is local.”*

# OPEN HARDWARE STATEMENT

This publication is a complete disclosure of the Modular Thermal Flywheel Stack and Gradient Governance System — its mechanical architecture, material specification, scale-integrated governance logic, and deployment framework.

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This system was designed to be material-agnostic by intent. The thermal mass component — the core functional element of the meso-scale flywheel stack — is specified by thermal property thresholds, not by named materials. Any naturally occurring or manufactured material meeting those thresholds qualifies. Marble qualifies. Limestone qualifies. Dense concrete qualifies. Reclaimed basalt qualifies. The specification is deliberately written so that a builder in any geography can look at what is locally available and determine for themselves whether it qualifies. No supply chain dependency is required. No licensed material is required. What is under your feet may already be the answer.

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### Citation

*Dunn, James E. (2026). Modular Thermal Flywheel Stack and Gradient Governance System: Material-Agnostic Open Hardware Disclosure. 39 North LLC. Zenodo. [https://doi.org/\[DOI assigned on upload\]](https://doi.org/[DOI assigned on upload])*

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## ABSTRACT

A modular thermal flywheel stack and gradient governance system for data center and high-performance computing thermal management. The system operates across three physical scales — micro (chip package), meso (rack-level stack), and macro (facility-level routing network) — within a unified governed architecture.

The central departure from conventional cooling systems is a shift from thermal rejection to thermal governance: heat is not expelled as waste but absorbed, buffered, routed, and allocated as a recoverable resource. The gradient governance principle — coordinated management of thermal gradients across scales to smooth volatility and enable intentional allocation — is the architectural claim.

The meso-scale flywheel stack is specified by thermal property thresholds. Any material with sufficient volumetric heat capacity and appropriate thermal conductivity qualifies as the thermal mass element. A complete material qualification table is included in Section 4 so that builders in any geography can identify locally available qualifying materials without supply chain dependency.

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## 1. FIGURES

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### Figure 1 — Macro Scale: Thermal Energy Routing Network

Server racks generate heat that is collected via a primary coolant loop, passed through a heat exchanger, and routed into the thermal flywheel tank. From the tank, thermal energy is distributed intentionally to building hot water systems, absorption chillers, and seasonal storage via controllable branch valves. Heat is not rejected — it is allocated.

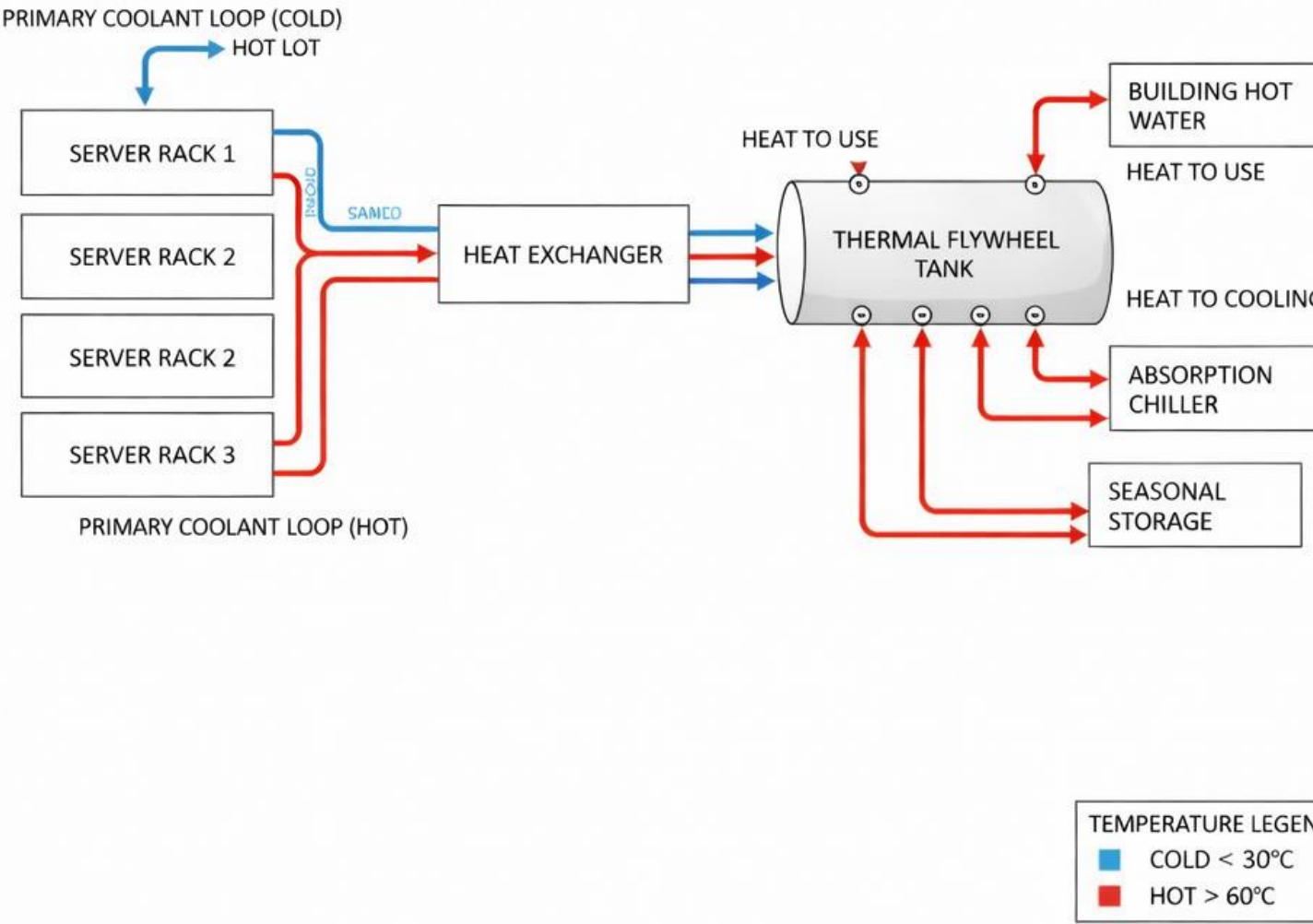
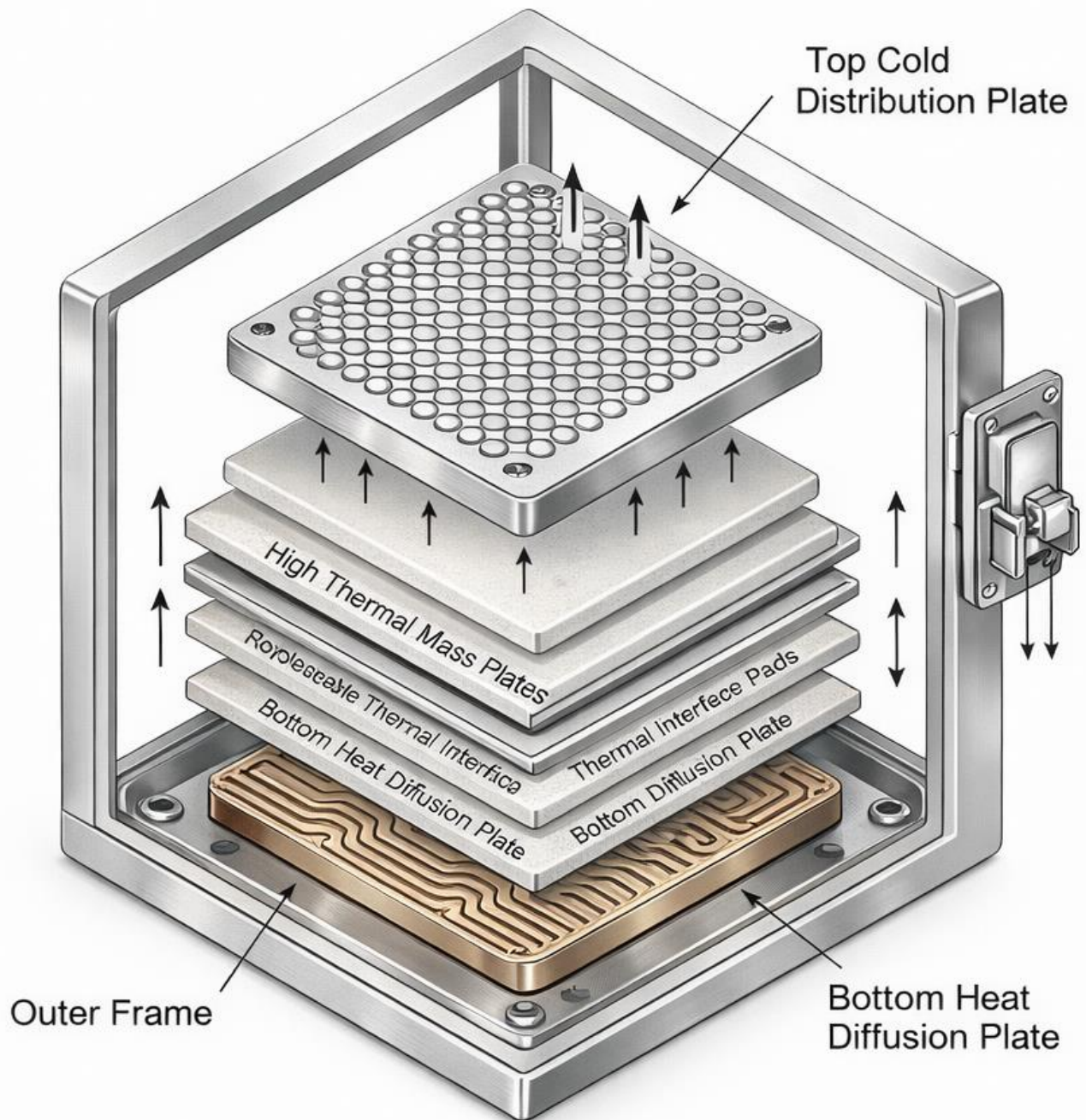


FIG. 1 — Macro scale: thermal energy routing network. Server racks → heat exchanger → thermal flywheel tank → building hot water, absorption chiller, seasonal storage.

## Figure 2 — Meso Scale: Modular Thermal Flywheel Stack

The flywheel stack comprises a top cold distribution plate with uniform contact array, multiple high thermal mass plates separated by replaceable interface pads, and a bottom heat diffusion plate with structured micro-pathways. The outer frame provides rigid precision enclosure. Thermal mass plate material is specified by property threshold — see Section 4 for qualifying materials.

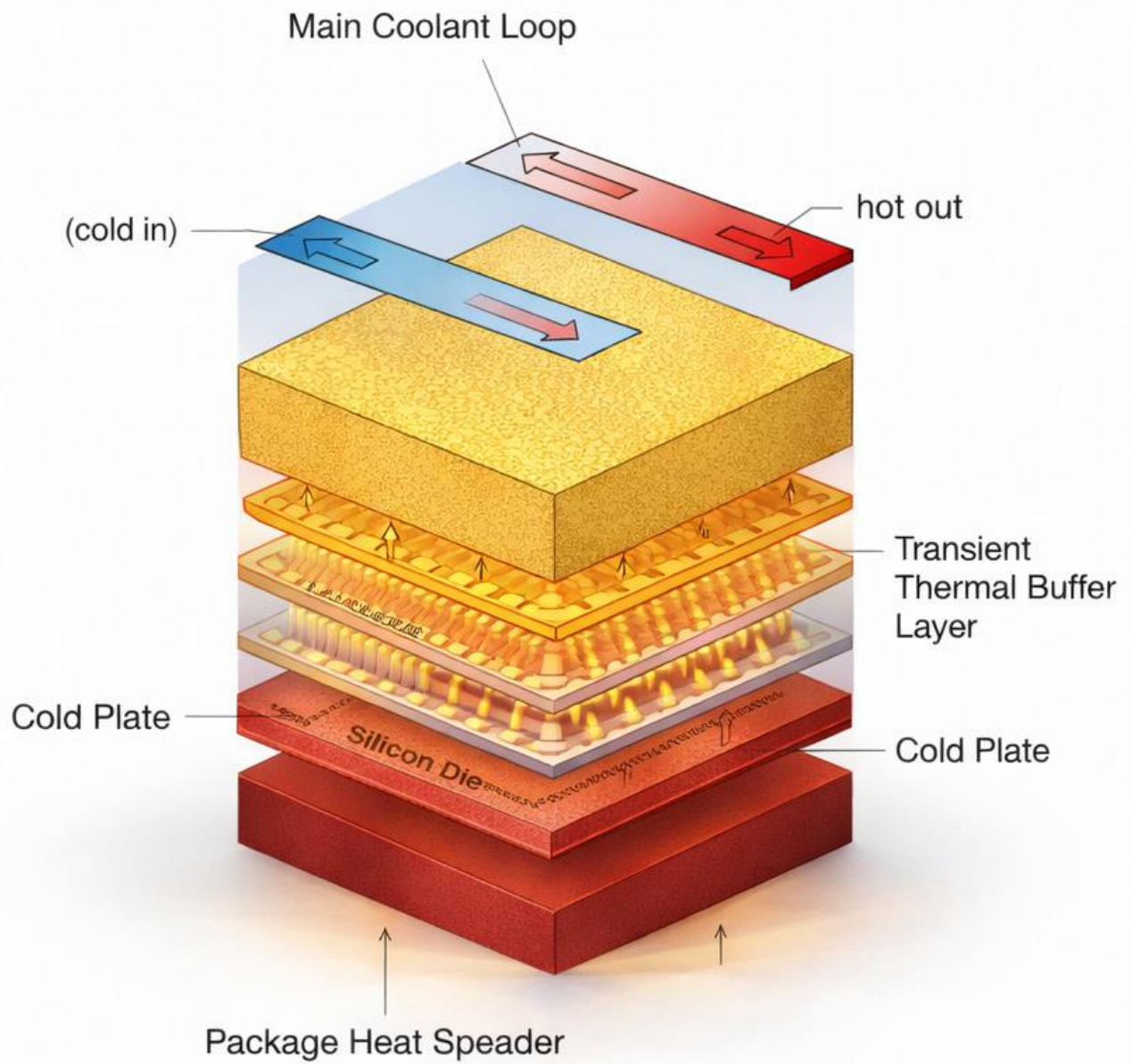


*FIG. 2 — Meso scale: modular flywheel stack. Top cold distribution plate, high thermal mass plates, replaceable interface pads, bottom heat diffusion plate, outer precision frame.*

### **Figure 3 — Micro Scale: Transient Thermal Buffer Layer**

A transient thermal buffer layer is positioned between the silicon die and the cold plate in the chip package stack. The buffer comprises an engineered material with internal microstructure — phase change material, lattice ceramic, or metal matrix composite — configured to absorb and moderate temperature spikes before they propagate through the thermal path. The package heat spreader forms the base of the assembly.





Conceptual representation – not to scale

FIG. 3 — Micro scale: transient thermal buffer layer between silicon die and cold plate. Package heat spreader at base. Main coolant loop at top. Cold in, hot out.

## 2. SYSTEM ARCHITECTURE

### 2.1 Gradient Governance Principle

Gradient governance is defined as the coordinated management of thermal gradients across multiple physical scales to smooth volatility, preserve thermal coherence, and enable intentional allocation of thermal energy rather than mere rejection.

Conventional cooling operates reactively: heat is detected after it accumulates and expelled. This system operates predictively and distributively: thermal energy is absorbed at the point of generation, buffered across the stack, and routed deliberately to destinations where it has recoverable value. The system treats the data center as a thermal power plant that happens to also run compute, not as a compute facility that generates inconvenient heat.

### 2.2 Micro Scale — Transient Thermal Buffer

The transient thermal buffer layer sits between the semiconductor chip package and the cold plate. Its function is to absorb transient temperature spikes before they propagate into the coolant loop, reducing both thermal gradient stress on the chip package and volatility in the macro-scale routing network.

- Position: between silicon die and cold plate in chip package stack
- Function: absorb and moderate temperature spikes, reduce thermal cycling stress on semiconductor joints and interconnects
- Material class: phase change material (PCM) with transition temperature near target operating range, lattice ceramic with high internal surface area, or metal matrix composite
- Specification basis: thermal diffusivity, phase transition enthalpy, operating temperature range

### 2.3 Meso Scale — Modular Thermal Flywheel Stack

The flywheel stack provides the primary thermal buffering mass at rack level. Multiple thermal mass plates are stacked within a rigid precision enclosure. Replaceable interface pads between plates ensure thermal contact without permanent bonding, enabling individual plate replacement without stack disassembly.

- Top cold distribution plate: uniform array of contact points ensures equal pressure and thermal distribution across the stack surface
- Thermal mass plates: high volumetric heat capacity material, specified by property threshold (see Section 4). Any qualifying material may be used.
- Replaceable interface pads: compressible, thermally conductive material conforming to surface irregularities and eliminating air gaps between plates
- Bottom heat diffusion plate: structured micro-pathways direct coolant flow through disciplined channels with extended dwell time for thermal transfer
- Outer precision frame: rigid enclosure maintaining alignment and contact pressure across the stack

### 2.4 Macro Scale — Thermal Energy Routing Network

The macro-scale network routes thermal energy from the rack-level heat exchanger into the thermal flywheel tank and from there to three distribution destinations. Controllable valves on each branch enable intentional allocation based on demand signals rather than indiscriminate rejection.

- Thermal flywheel tank: large thermal mass element providing facility-level buffering. Absorbs peak load. Releases to distribution branches on demand.
- Branch 1 — Building hot water: direct thermal energy recovery for building domestic hot water. Zero additional energy input required.
- Branch 2 — Absorption chiller: thermal energy drives absorption cooling cycle, converting waste heat into cooling capacity. The facility cools itself with its own heat.
- Branch 3 — Seasonal thermal storage: thermal energy stored in ground-coupled or insulated tank system for use in heating season. Shifts thermal value across time.



### 3. MATERIAL QUALIFICATION — THERMAL MASS PLATES

The thermal mass plates in the meso-scale flywheel stack are specified by thermal property threshold, not by named material. Any material meeting the following minimum thresholds qualifies for use as thermal mass plates in this system:

**MINIMUM QUALIFYING THRESHOLDS**

Volumetric heat capacity:  $\geq 1.5 \text{ MJ/m}^3\cdot\text{K}$   
Thermal conductivity:  $\geq 0.5 \text{ W/m}\cdot\text{K}$   
Continuous operating temperature:  $\geq 120^\circ\text{C}$  without structural degradation  
Surface workability: machinable or castable to flat surface within  $\pm 0.1 \text{ mm}$  tolerance for interface pad contact

The following table lists materials that meet these thresholds, with their typical property ranges, geographic availability, and build notes. This table is not exhaustive. Any material meeting the thresholds qualifies.

Material	Vol. Heat Cap. (MJ/m <sup>3</sup> ·K)	Conductivity (W/m·K)	Global Availability	Build Notes
Marble	2.1 – 2.3	2.5 – 3.0	Mediterranean, South Asia, Americas, Africa	High density, excellent surface finish. Quarried globally. Any grade qualifies.
Granite	2.4 – 2.7	2.5 – 4.0	Global — every continent	Widely available as offcut/scrap from construction. Thermal performance exceeds spec.
Limestone	1.9 – 2.2	1.5 – 2.0	Globally abundant	Softer than granite. Machine to tolerance easily. Abundant in North Africa, Middle East, Caribbean.
Basalt	2.5 – 2.9	1.5 – 2.5	Volcanic regions globally	Extremely dense. Available as cast basalt in industrial form. East Africa, Iceland, Pacific Rim.
Dense Concrete (high-mass mix)	1.8 – 2.2	1.0 – 1.8	Castable anywhere	Locally producible from aggregate. Mix design determines thermal properties. Lowest supply chain dependency of any option.
Fired Clay Brick (dense grade)	1.5 – 1.8	0.6 – 1.0	Global — manufacturable anywhere clay exists	Lowest-cost option. Dense-fired grades only — standard hollow brick does not qualify. Ubiquitous in South Asia, Sub-Saharan Africa.
Reclaimed Sandstone	1.7 – 2.0	1.0 – 2.0	Middle East, North Africa, North America, Europe	Often available as construction demolition material. Zero extraction required.
Cast Iron	3.5 – 3.7	40 – 60	Global industrial supply	Highest thermal conductivity of listed options. Industrial offcut widely available. Heavy — structural support required.
Aluminium Alloy	2.4 – 2.6	150 – 200	Global industrial supply	Very high conductivity. Manufactured material but

				globally accessible. Recycled aluminium qualifies.
<b>Phase Change Material (PCM)</b>	120–300 MJ/m <sup>3</sup> (latent heat)	0.2 – 0.6	Specialty supply	For micro-scale buffer layer only. Paraffin, salt hydrates, fatty acids. Manufactured — not locally sourceable in most regions.

**NOTE FOR BUILDERS** — If you are reading this anywhere in the world and you have access to local stone, dense brick, cast iron offcuts, or high-mass construction aggregate: you may already have your thermal mass material. Test it against the thresholds above. The specification is the threshold. The material is yours to choose.

## 4. ARCHITECTURAL DISCLOSURES

The following disclosures establish prior art in the public record. No patent is claimed. Each disclosure is freely usable under CC BY 4.0.

### Disclosure 1 — Gradient Governance Principle

Coordinated management of thermal gradients across micro, meso, and macro physical scales within a single unified architecture. Thermal energy treated as an allocable resource rather than waste. Volatility smoothed at each scale before propagating to the next. Cross-scale coherence maintained through governed routing rather than reactive rejection.

#### Disclosure 1

*Gradient governance: coordinated multi-scale thermal management treating heat as allocable resource. Volatility absorption at micro scale, buffering at meso scale, intentional routing at macro scale. Three scales governed as one architecture.*

### Disclosure 2 — Transient Thermal Buffer Layer (Micro Scale)

A material layer between the semiconductor chip package and cold plate comprising an engineered composite with internal microstructure configured to absorb transient temperature spikes before propagation. Phase change materials, lattice ceramics, or metal matrix composites qualifying by thermal diffusivity and phase transition enthalpy. Reduces thermal cycling stress on chip package joints and interconnects. Extends component operational life.

#### Disclosure 2

*Transient thermal buffer layer between chip die and cold plate. Absorbs temperature spikes before propagation. Qualifying materials: PCM, lattice ceramic, metal matrix composite. Reduces thermal gradient stress on semiconductor packages. Extends component life.*

### Disclosure 3 — Modular Thermal Flywheel Stack with Replaceable Interface Layers (Meso Scale)

A stacked assembly of high-thermal-mass plates in a rigid precision enclosure. Top cold distribution plate with uniform contact array. Replaceable compressible interface pads between plates eliminating air gaps without permanent bonding. Bottom heat diffusion plate with structured micro-pathways and extended coolant dwell time.

Material-agnostic: thermal mass plates specified by volumetric heat capacity and conductivity thresholds. Any qualifying material — natural stone, cast concrete, dense ceramic, metal alloy — may be used.

**Disclosure 3**

*Modular flywheel stack: top cold distribution plate, thermal mass plates (material-agnostic, property-threshold specified), replaceable interface pads, bottom heat diffusion plate with micro-pathways, rigid precision frame. Thermal mass plates replaceable individually. Any material meeting  $VHC \geq 1.5 \text{ MJ/m}^3\cdot\text{K}$  and conductivity  $\geq 0.5 \text{ W/m}\cdot\text{K}$  qualifies.*

**Disclosure 4 — Thermal Energy Routing Network with Intentional Allocation (Macro Scale)**

A thermal flywheel tank coupled to a heat exchanger receiving heat from a primary coolant loop. Three controllable distribution branches: building hot water, absorption chiller, and seasonal thermal storage. Controllable valves on each branch enable intentional demand-driven allocation. Thermal energy is routed to value-generating destinations rather than expelled to the environment.

**Disclosure 4**

*Macro-scale thermal routing network: flywheel tank receives heat from primary loop via heat exchanger. Three controlled distribution branches: building hot water, absorption chiller, seasonal storage. Demand-driven allocation via controllable branch valves. Heat rejection replaced by heat routing.*

**Disclosure 5 — Material-Agnostic Thermal Mass Specification**

A thermal mass specification framework defined by qualifying property thresholds rather than named materials. Minimum volumetric heat capacity  $1.5 \text{ MJ/m}^3\cdot\text{K}$ , minimum thermal conductivity  $0.5 \text{ W/m}\cdot\text{K}$ , continuous operating temperature minimum  $120^\circ\text{C}$ , surface workability to flat tolerance within  $\pm 0.1 \text{ mm}$ . Any naturally occurring or manufactured material meeting these thresholds qualifies. This specification is deliberately designed to prevent material enclosure: no single material, supply chain, or territory is required. Local geology is sufficient.

**Disclosure 5**

*Thermal mass specification by property threshold, not material name.  $VHC \geq 1.5 \text{ MJ/m}^3\cdot\text{K}$ , conductivity  $\geq 0.5 \text{ W/m}\cdot\text{K}$ , operating temp  $\geq 120^\circ\text{C}$ , surface workability  $\pm 0.1 \text{ mm}$ . Qualifying materials include marble, granite, limestone, basalt, dense concrete, dense fired brick, sandstone, cast iron, aluminium alloy. Local sourcing explicitly enabled. No licensed material required.*

**Disclosure 6 — Cross-Scale Integration Architecture**

Integration of micro, meso, and macro thermal management within a single governed system. Volatility absorbed at chip level prevents propagation to rack level. Buffering at rack level prevents propagation to facility level. Facility-level routing converts what would be cumulative thermal load into distributed thermal value. Each scale governs the one above it. The architecture is the claim — not any individual scale component.

**Disclosure 6**

*Cross-scale integration: micro buffer prevents spike propagation to meso stack. Meso stack prevents volatility propagation to macro network. Macro network routes thermal value to demand destinations. Three scales governed as one coherent architecture. No single scale component is sufficient alone.*

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## 5. DISCLOSURE SUMMARY

#	Title	Scale	Status
1	Gradient Governance Principle	System-wide	Open — CC BY 4.0
2	Transient Thermal Buffer Layer	Micro scale	Open — CC BY 4.0
3	Modular Flywheel Stack + Replaceable Interface Layers	Meso scale	Open — CC BY 4.0
4	Thermal Energy Routing Network with Intentional Allocation	Macro scale	Open — CC BY 4.0
5	Material-Agnostic Thermal Mass Specification	Meso scale	Open — CC BY 4.0
6	Cross-Scale Integration Architecture	System-wide	Open — CC BY 4.0

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## 6. CLOSING NOTE

This system was designed to govern heat the way heat wants to be governed — not expelled, absorbed. Not wasted, routed. Not controlled by scarcity, freed by specification.

The material table in Section 3 is the most important part of this document. Not because stone is the invention. Because the specification that makes stone sufficient is the invention. The design makes what is already present everywhere in the world eligible to do useful work.

You do not need a supply chain. You do not need a license. You do not need a quarry in a country that hasn't been annexed yet.

You need the thresholds and whatever is under your feet.

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